

AMENDMENTS TO THE ABSTRACT:

Please replace the Abstract originally appearing on page 13 of the application with the following rewritten paragraph:

ABSTRACT OF THE DISCLOSURE

A conductive plastic lead frame and method of manufacturing, the same suitable for use in IC packaging. In a preferred embodiment, the lead frame is constructed of a plastic or polymer based lead frame structure with an intrinsic conductive polymer coating. In a second embodiment, the lead frame is a composite plastic or polymeric material intermixed with an intrinsic conductive polymer coating.